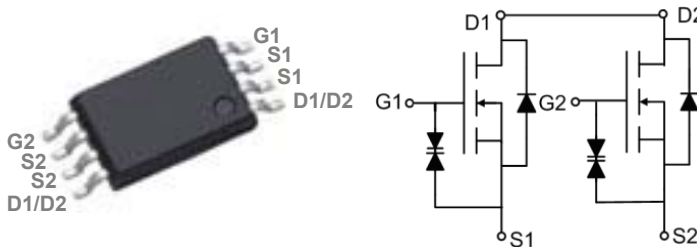# PDEW2210

20V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
20V	12mΩ	7.5A

Features

- *20V, 7.5A, RDS(ON)=12mΩ@VGS=4.5V*
- *Improved dv/dt capability*
- *Fast switching*
- *Green Device Available*
- *Suit for 1.8V Gate Drive Applications*
- *G-S ESD protection diode embedded*

TSSOP8 Dual Pin Configuration

Applications

- *Notebook*
- *Load Switch*
- *LED applications*

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	±10	V
I_D	Drain Current – Continuous (T_C=25℃)	7.5	A
	Drain Current – Continuous (T_C=100℃)	4.7	A
I_{DM}	Drain Current – Pulsed[1]	30	A
P_D	Power Dissipation (T_C=25℃)	1.25	W
	Power Dissipation – Derate above 25℃	0.01	W/℃
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{θJA}$	Thermal Resistance Junction to ambient	---	100	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	20	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.02	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=20V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=16V , V_{GS}=0V , T_J=125℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±10V , V_{DS}=0V	---	---	±10	uA

On Characteristics

			Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=4.5V , I_D=5A	7	10	12	mΩ
		V_{GS}=2.5V , I_D=3A	8	11	14	
		V_{GS}=1.8V , I_D=2A	9	13	20	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	0.3	0.6	1	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	2	---	mV/℃
gfs	Forward Transconductance	V_{DS}=10V , I_S=5A	---	11	---	S

Dynamic and switching Characteristics

			Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge[2,3]	V_{DS}=10V , V_{GS}=4.5V , I_D=5A	---	16.9	26	nC
Q_{gs}	Gate-Source Charge[2,3]		---	1.1	3	
Q_{gd}	Gate-Drain Charge[2,3]		---	4	7	
$T_{d(on)}$	Turn-On Delay Time[2,3]	V_{DD}=10V , V_{GS}=4.5V , R_G=25Ω I_D=1A	---	6.8	13	nS
T_r	Rise Time[2,3]		---	20	38	
$T_{d(off)}$	Turn-Off Delay Time[2,3]		---	41.8	79	
T_f	Fall Time[2,3]		---	13.2	25	
C_{iss}	Input Capacitance	V_{DS}=10V , V_{GS}=0V , F=1MHz	---	1020	1480	pF
C_{oss}	Output Capacitance		---	160	240	
C_{rss}	Reverse Transfer Capacitance		---	110	160	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	7.5	A
I_{SM}	Pulsed Source Current		---	---	30	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V

Note :
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
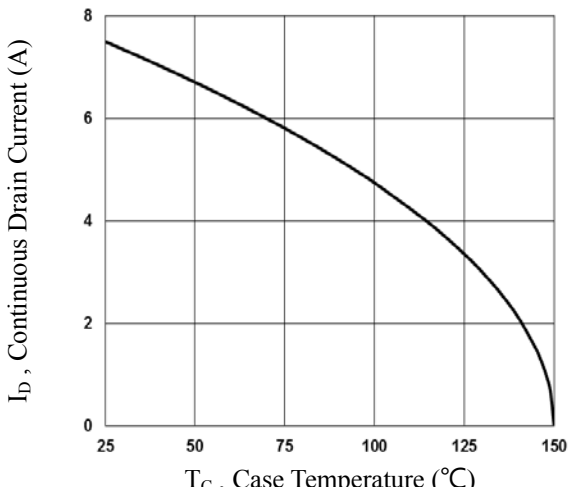3. Essentially independent of operating temperature.
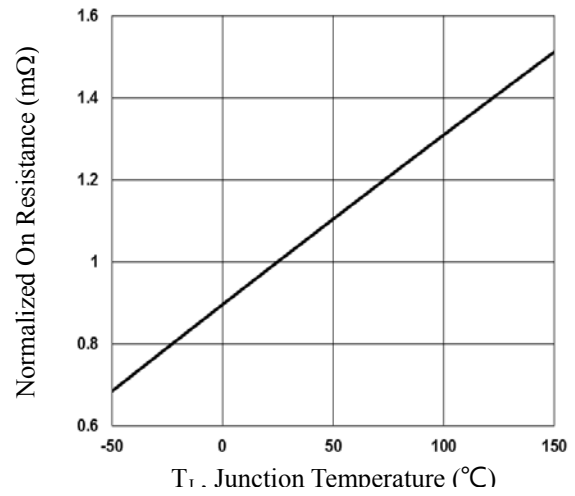
Fig.1 Continuous Drain Current vs. T$_C$
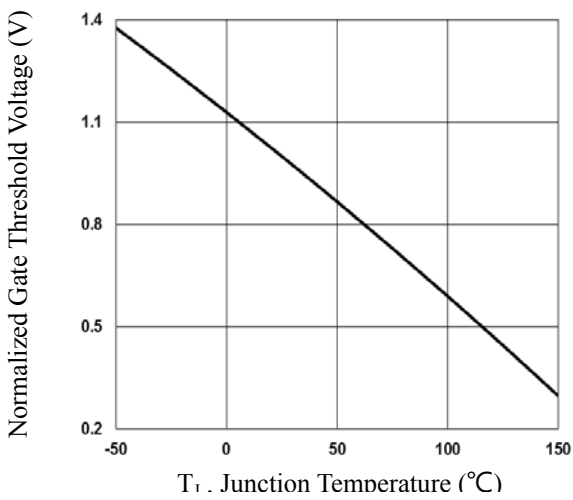

Fig.2 Normalized RDSON vs. T$_J$
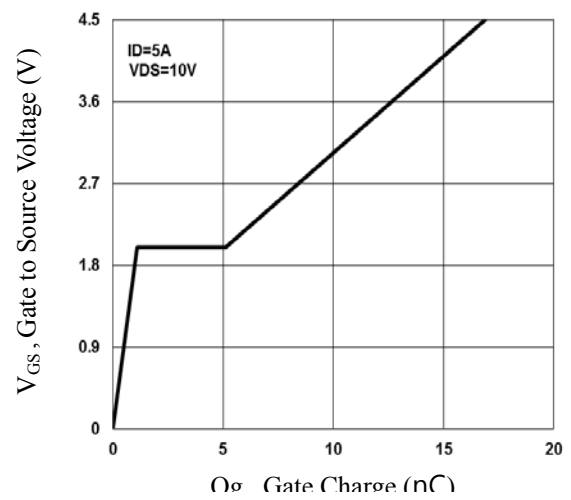

Fig.3 Normalized V$_{th}$ vs. T$_J$
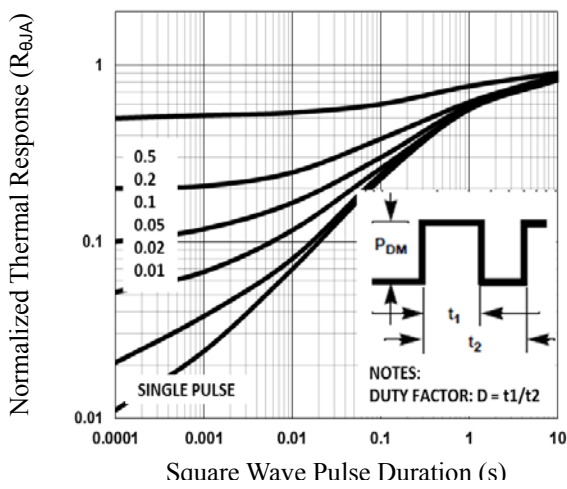

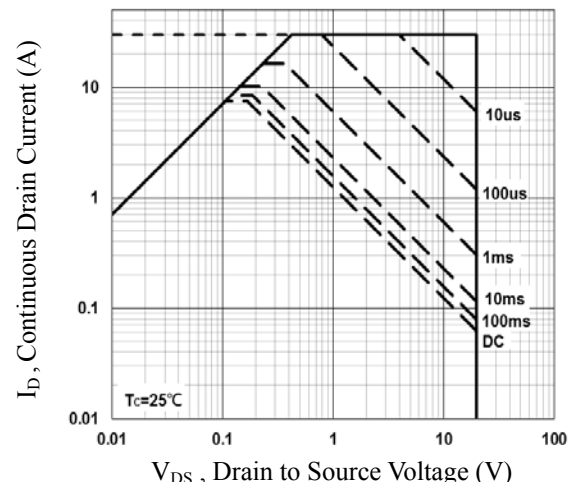Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

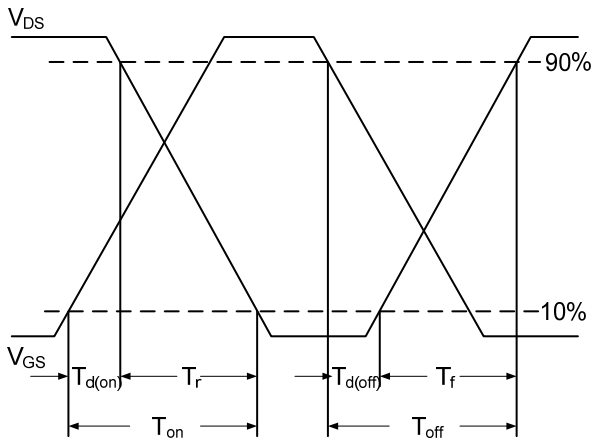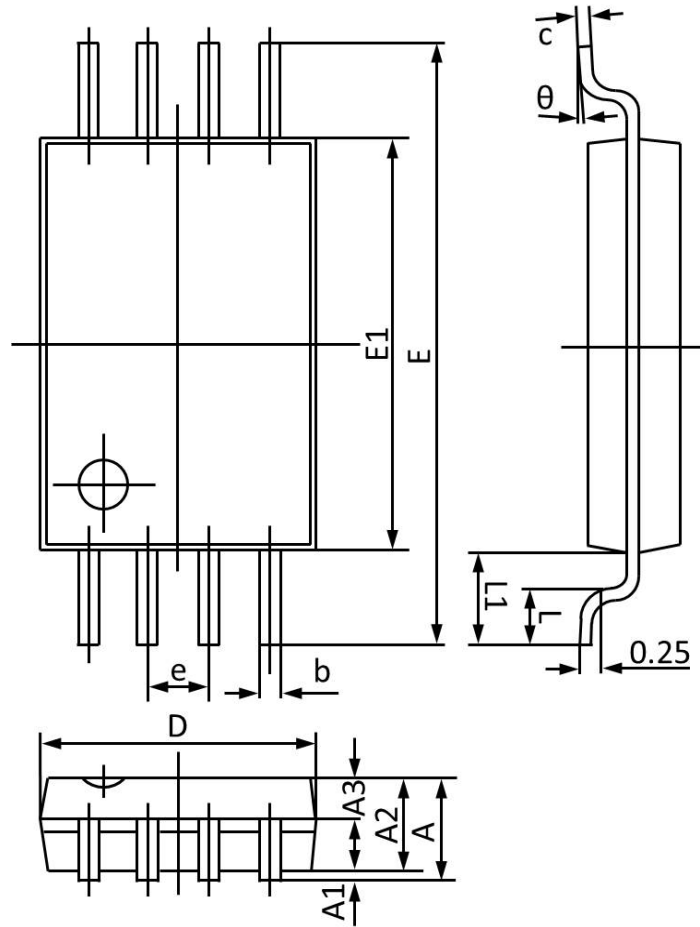Fig.6 Maximum Safe Operation Area

Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

TSSOP8 PACKAGE INFORMATION

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.100	1.200	0.044	0.047
A1	0.050	0.150	0.002	0.006
A2	0.900	1.050	0.036	0.041
A3	0.390	0.490	0.016	0.019
b	0.210	0.300	0.009	0.011
c	0.130	0.190	0.006	0.007
D	0.120	0.140	0.004	0.006
E	6.200	6.600	0.244	0.260
E1	4.300	4.500	0.169	0.177
e	0.650(BSC)		0.025(BSC)	
L	0.450	0.750	0.018	0.029
L1	1.000(BSC)		0.039(BSC)	
θ	0°	8°	0°	8°